Exam.Code:1030 Sub. Code: 7857

## 2072

## M.Tech. (Material Science and Technology) Second Semester

MT-202: Semiconductor Devices and Technology

Time allowed: 3 Hours

Max. Marks: 50

NOTE: Attempt five questions in all, including Question No. I which is compulsory and selecting two questions from each Section.

x-x-x

1. Attempt the following parts:

- (a) When does an intrinsic semiconductor behave as an insulator?
- (b) What is a load line for a transistor?
- (c) What does the term work-function signify for an MOS structure?
- (d) What is effective segregation coefficient?
- (e) Differentiate between positive and negative photoresists.

(5×2)

Section A

- (a) Mark the Fermi level for (i) an intrinsic semiconductor (ii) n-type semiconductor and 2. (iii) p- type semiconductor. Describe the behaviour and properties of conductor, insulators and semiconductors on the basis of band theory.
  - (b) Prove that the effective mass of an electron in an crystal is given by

$$m^* = \frac{h^2}{\frac{d^2 E}{dk^2}}$$

(6,4)

- (a) Define h-parameters. Outline the method of obtaining h- parameters in CE . 3. configuration.
  - (b) Describe the construction and working of Heterojunction bipolar transistor.
- (a) Show the formation of accumulation layer, depletion layer, and inversion layer in a MOS structure formed on p-type semiconductor using suitable energy band diagram.
  - (b) What do you understand by a depletion-type MOSFET?

(7,3)

## Section B

- (a) Briefly describe the metal organic chemical vapour deposition (MOCVD) processes 5. to grow thin films of GaAs.
  - (b) Describe the following processes (i) Polysilicon deposition (ii) Metallization.
- (a) With suitable schematics, explain shadow printing and projection printing lithography methods. Cite the factors, which affect the resolution of photolithography.
  - (b) Explain the process of aluminium etching. Write the chemical reaction involved in chemical etching process.

(6,4)

- (a) Discuss the basic diffusion laws, common diffusion sources, and drive-in process in 7. semiconductors.
  - (b) Describe Ion implantation doping technique. Discuss its advantages. (6,4)